

Abstract

The present application relates to a vacuum suction system and a method. The vacuum suction system is used for sucking and releasing a wafer located on a bearing surface of a vacuum suction heater in a reaction chamber. The reaction chamber has an extraction port, and the vacuum suction heater has a ventilation port. The vacuum suction system comprises: a first pipeline, for fluid coupling the extraction port of the reaction chamber with a vacuum pump; a second pipeline, for fluid coupling the ventilation port of the vacuum suction heater with the vacuum pump; and a third pipeline, connected to the second pipeline and used for supplying gas from a gas source to the vacuum suction system. When sucking the wafer by the vacuum suction system, the air pressure in the suction pipeline inside the heater can be easily adjusted during the sucking and releasing process of the wafer, thereby adjusting the pressure difference between the back side and front side of the wafer, which is beneficial for improving work efficiency.